



Express Mail No.: EL 500 575 771 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Fukutomi et al.

Serial No.: 10/042,408

Group Art Unit: 2812

Filed: January 8, 2002

Examiner: Nema Berezny

For: FABRICATION PROCESS OF  
SEMICONDUCTOR PACKAGE AND  
SEMICONDUCTOR PACKAGE

Attorney Docket No.: 7426-082

New York, NY

August 27, 2002

TECHNOLOGY CENTER 2800  
AUG 30 2002

RECEIVED

**SECOND SUBMISSION OF FORMAL DRAWINGS**

Assistant Commissioner for Patents

**Attn.: Draftsman**

Washington, D.C. 20231

Sir:

Per conversation with Examiner Berezny on August 23, 2002, Applicants would like to substitute the drawings submitted on October 23, 2001 ("original drawings"), with a set of drawings attached hereto ("substitute drawings") because the hatching in the original drawings has unnecessary lines. Please see, for example, reference number 3 in Fig. 1. Also the corresponding portions should have same hatching in Figs 20 and 21, those are different in the original drawings. In Fig. 11, although each end of one of the two wire bonds(100) is inadvertently depicted as entering into the wiring (2), it should correctly ends on the wiring (2) as shown on the other ends. Since those errors are of clerical nature, the substitute drawings do not include new matter. Applicants respectfully request that the original drawings be replaced with the substitute drawings attached hereto in the above-identified case.

No fee is believed to be due for this submission. However, should any fee be required, please charge such fee to Pennie & Edmonds LLP Deposit Account No. 16-1150.

Respectfully submitted,

Date: August 27, 2002

Charles E. Miller

24,576

(Reg. No.)

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Enclosure